ON Semiconductor				
Base Part		FAN3225T	HF	Pb-free
Orderable Part		FAN3225TMPX	Total weight (mg)	21.61987
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	1.055	Silicon (Si)	7440-21-3	10
Die Attach		Bis(a,a-dimethylbenzyl) Peroxide	80-43-3	0.9
		Isobornyl Methacrylate	7534-94-3	
		Silver (Ag)	7440-22-4	81.
		Isobornyl Acrylate	5888-33-5	
	0.1359	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2	(
Lead Frame		Zinc (Zn)	7440-66-6	0.1244119
		Iron (Fe)	7439-89-6	2.3491897
		Copper (Cu)	7440-50-8	97.44380554
	9.565	Phosphorus (P)	7723-14-0	0.08259279
Mold Compound- Black		Carbon Black (C)	1333-86-4	0.9
		Fused Silica (SiO2)	60676-86-0	88
		Ortho Cresol Novolac Resin	29690-82-2	6.5
	10.33327	Phenolic Resin (Novolac)	9003-35-4	ť
Plating		Silver (Ag)	7440-22-4	1.57068063
		Palladium (Pd)	7440-05-3	3.59012715
		Nickel (Ni)	7440-02-0	92.8197457
	0.1337	Gold (Au)	7440-57-5	2.01944652
Wire Bond - Au	0.397	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF